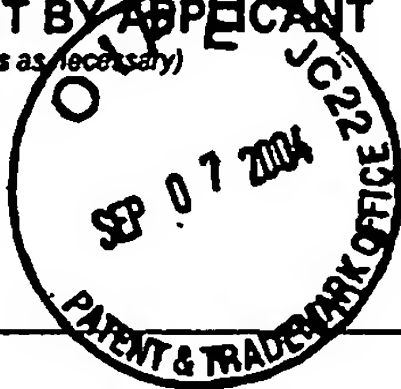


Substitute for form 1449/PTO
**INFORMATION DISCLOSURE
 STATEMENT BY APPLICANT**
 (Use as many sheets as necessary)



Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

PTO/SB/08A(10-01)
 Approved for use through 10/31/2002. OMB 05-0031
 US Patent & Trademark Office, U.S. DEPARTMENT OF COMMERCE

Complete if Known

Application Number 10/602322

Filing Date June 24, 2003

First Named Inventor Farrar, Paul

Group Art Unit 1763

Examiner Name Unknown

Sheet 1 of 1

Attorney Docket No: 1303.096US1

US PATENT DOCUMENTS

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date if Appropriate
JP	US2001/0014524	08/16/2001	Farrar, Paul A.	438	613	02/19/1999
	US2002/0034581	03/21/2002	Farrar, Paul A., et al.	427	58	02/20/2001
	US-3,959,047	05/25/1976	Alberts, G. S., et al.	156	8	09/30/1974
	US-5,457,345	10/10/1995	Cook, H. C., et al.	257	766	01/14/1994
	US-5,461,257	10/24/1995	Hundt, M. J.	257	707	03/31/1994
	US-5,642,261	06/24/1997	Bond, R. H., et al.	361	704	06/30/1994
	US-5,693,572	12/02/1997	Bond, R. H., et al.	437	209	01/18/1996
	US-6,136,689	10/24/2000	Farrar, Paul A.	438	626	08/14/1998
JP	US-6,435,396	08/20/2002	Eldridge, Jerome M.	228	33	04/10/2000

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²
--------------------	---------------------	------------------	---	-------	----------	----------------

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
JP		ANONYMOUS, "Combination Process for Final Metal Lines and Metal Terminals", Kenneth Mason Publications Ltd, Research Disclosure No. 342, England,(Oct. 1992),1 page	
		ANONYMOUS, "Process for High Density of Chip Terminals on Large Wafers", Kenneth Mason Publications Ltd, Research Disclosure No. 02, England,(Feb. 1993),1 page	
		BABIARZ, A J., "Key Process Controls for Underfiling Flip Chips", <u>Solid State Technology</u> , 40(4), (April 1997),77-8, 81, 83	
		JONES, P , et al., "Bumped Wafers, Worth Their Weight in Gold?", <u>Advanced Packaging</u> , 8(1), (January 1997),54-57	
		MARCOTTE, V. C., "Review of Flip Chip Bonding", <u>Proceedings of the 2nd ASM International Electronic Materials and Processing Congress</u> , 24-28 April 1989, Philadelphia, PA, (1989),73-81	
		MINGES, MERRILL , "Electronic Materials Handbook", <u>Materials Park, OH : ASM International</u> , (1989),301, 440	
		PUTTLITZ, KARL J., et al., "Solder Transfer Technique for Flip-Chip and Electronic Assembly Applications", <u>IEEE Transactions on Components, Packaging and Manufacturing Technology</u> , Part C, Volume 21, No. 3, (July 1998),182-188	
JP		RYAN, J. G., "Technology Challenges for Advanced Interconnects", <u>Advances in Metallization and Interconnect Systems for ULSI Applications</u> , September 30 - October 2, 1997, San Diego CA, (1997),1-5	

EXAMINER

DATE CONSIDERED

8/28/06

Substitute Disclosure Statement Form (PTO-1449)

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. 1 Applicant's unique citation designation number (optional) 2 Applicant is to place a check mark here if English language Translation is attached